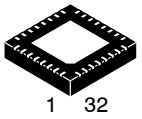
NB4N111K

Clock Fanout Buffer, 1:10 Differential, 3.3 V, with HCSL Level Output

ON Semiconductor®

http://onsemi.com



QFN32
MN SUFFIX
CASE 488AM

Description

The NB4N111K is a differential input clock 1 to 10 HCSL fanout buffer, optimized for ultra low propagation delay variation. The NB4N111K is designed with HCSL clock distribution for FBDIMM applications in mind.

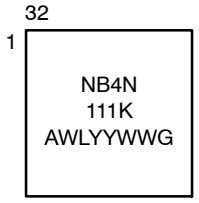
Inputs can accept differential LVPECL, CML, or LVDS levels. Single−ended LVPECL, CML, LVCMOS or LVTTL levels are accepted with the proper V_{REFAC} supply (see Figures 5, 10, 11, 12, and 13). Clock input pins incorporate an internal 50 Ω on die termination resistors. Outputs can interface with LVDS with proper termination (See Figure 15).

The NB4N111K specifically guarantees low output−to−output skews. Optimal design, layout, and processing minimize skew within a device and from device to device. System designers can take advantage of the NB4N111K's performance to distribute low skew clocks across the backplane or the motherboard.

Features

- Typical Input Clock Frequencies: 100, 133, 166, 200, 266, 333, and 400 MHz
- 340 ps Typical Rise and Fall Times
- 800 ps Typical Propagation Delay
- Δtpd 100 ps Maximum Propagation Delay Variation Per Each Differential Pair
- <1 ps RMS Additive Clock jitter
- Operating Range: V_{CC} = 3.0 V to 3.6 V with V_{EE} = 0 V
- Differential HCSL Output Level or LVDS with Proper Termination
- These are Pb−Free Devices

MARKING DIAGRAM*



A	= Assembly Site
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb−Free Package

*For additional marking information, refer to Application Note AND8002/D.

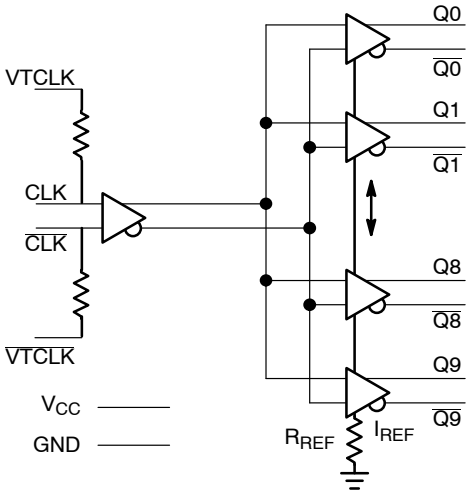


Figure 1. Pin Configuration (Top View)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

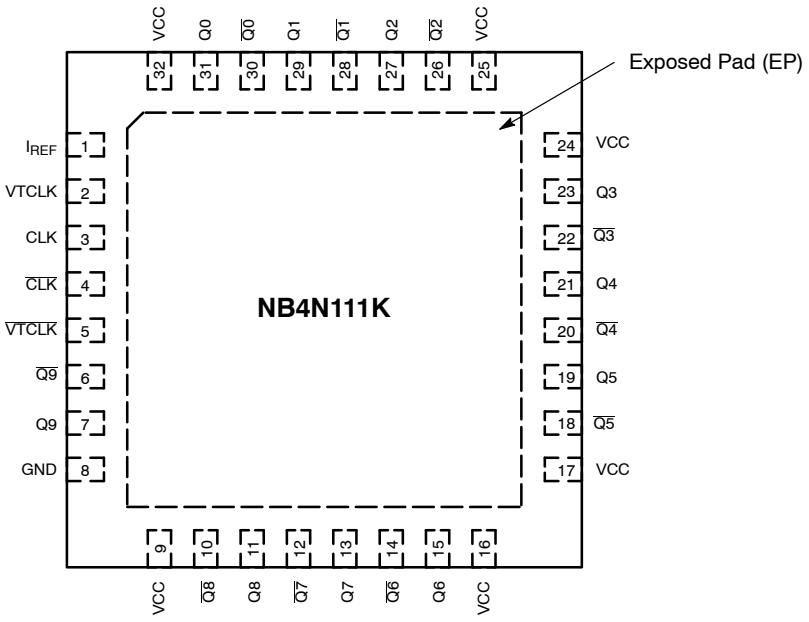


Figure 2. Pinout Configuration (Top View)

Table 1. PIN DESCRIPTION

Pin	Name	I/O	Description
1	I_{REF}	Output	Output current programming pin. Connect to GND. (See Figure 9).
2, 5	VTCLK, $\overline{VTCLK}$	–	Internal 50 Ω Termination Resistor connection Pins. In the differential configuration when the input termination pins are connected to the common termination voltage, and if no signal is applied then the device may be susceptible to self−oscillation.
3	CLK	LVPECL Input	CLOCK Input (TRUE)
4	$\overline{CLK}$	LVPECL Input	CLOCK Input (INVERT)
8	GND	–	Supply Ground. GND pin must be externally connected to power supply to guarantee proper operation.
9, 16, 17, 24, 25, 32	V_{CC}	–	Positive Supply pins. V_{CC} pins must be externally connected to a power supply to guarantee proper operation.
6, 10, 12, 14, 18, 20, 22, 26, 28, 30	$\overline{Q[09-0]}$	HCSL or LVDS Output	Noninverted Clock Output. (For LVDS levels see Figure 15)
7, 11, 13, 15, 19, 21, 23, 27, 29, 31	Q[09−0]	HCSL or LVDS Output	Inverted Clock Output. (For LVDS levels see Figure 15)
Exposed Pad	EP	GND	Exposed Pad. The thermally exposed pad (EP) on package bottom (see case drawing) must be attached to a sufficient heat−sinking conduit for proper thermal operation. (Note 1)

1. The exposed pad must be connected to the circuit board ground.

Table 2. ATTRIBUTES

Characteristic		Value
Input Default State Resistors		None
ESD Protection	Human Body Model	>2 kV
Moisture Sensitivity (Note 2)	QFN32	Level 1
Flammability Rating Oxygen Index: 28 to 34		UL 94 V−0 @ 0.125 in
Transistor Count		622
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test		

2. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS (Note 3)

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	Positive Power Supply	GND = 0 V		4.6	V
V_I	Positive Input	GND = 0 V		GND − 0.3 ≤ V_I ≤ V_{CC}	V
V_{INPP}	Differential Input Voltage |CLK − $\overline{CLK}$|			V_{CC}	V
I_{OUT}	Output Current	Continuous Surge		50 100	mA mA
T_A	Operating Temperature Range	QFN32		−40 to +70	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction−to−Ambient) (Note 3)	0 lfpm 500 lfpm	QFN32 QFN32	31 27	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	2S2P (Note 4)	QFN32	12	°C/W
T_{sol}	Wave Solder Pb−Free			265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

3. JEDEC standard 51−6, multilayer board − 2S2P (2 signal, 2 power).
4. JEDEC standard multilayer board − 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 4. DC CHARACTERISTICS (V_{CC} = 3.0 V to 3.6 V, T_A = −40°C to +70°C Note 5)

Symbol	Characteristic	Min	Typ	Max	Unit
I_{GND}	GND Supply Current (All Outputs Loaded)	70	98	120	mA
I_{CC}	Power Supply Current (All Outputs Loaded)			300	mA
I_{IH}	Input HIGH Current CLKx, $\overline{CLKx}$		2.0	150	μA
I_{IL}	Input LOW Current CLKx, $\overline{CLKx}$	−150	−2.0		μA
DIFFERENTIAL INPUT DRIVEN SINGLE−ENDED (Figures 5 and 7)					
V_{th}	Input Threshold Reference Voltage Range (Note 6)	1050		V_{CC} − 150	mV
V_{IH}	Single−Ended Input HIGH Voltage	V_{th} + 150		V_{CC}	mV
V_{IL}	Single−Ended Input LOW Voltage	GND		V_{th} − 150	mV
DIFFERENTIAL INPUTS DRIVEN DIFFERENTIALLY (Figures 6 and 8)					
V_{IHD}	Differential Input HIGH Voltage	1200		V_{CC}	mV
V_{ILD}	Differential Input LOW Voltage	GND		V_{CC} − 75	mV
V_{ID}	Differential Input Voltage (V_{IHD} − V_{ILD})	75		2400	mV
V_{CMR}	Input Common Mode Range	1163		V_{CC} − 75	
HCSL OUTPUTS (Figure 4)					
V_{OH}	Output HIGH Voltage	600	740	900	mV
V_{OL}	Output LOW Voltage	−150	0	150	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Input parameters vary 1:1 with V_{CC}. Measurements taken with all outputs loaded 50 Ω to GND, see Figure 9.
6. V_{th} is applied to the complementary input when operating in single ended mode.

Table 5. AC CHARACTERISTICS V_{CC} = 3.0 V to 3.6 V, GND = 0 V; −40°C to +70°C (Note 7)

Symbol	Characteristic		Min	Typ	Max	Unit
V_{OUTPP}	Output Voltage Amplitude (@ $V_{INPPmin}$)	f_{in} = 400 MHz		725	1000	mV
t_{PLH}, t_{PHL}	Propagation Delay to (See Figure 3)	CLK/$\overline{CLK}$ to Qx/$\overline{Qx}$	550	800	1100	ps
Δt_{PLH}, Δt_{PHL}	Propagation Delay Variations Variation Per Each Diff Pair CLK/$\overline{CLK}$ to Qx/$\overline{Qx}$ (Note 8) (See Figure 3)				100	ps
t_{SKEW}	Duty Cycle Skew (Note 9) Within−Device Skew Device−to−Device Skew (Note 10)				20 100 150	ps ps ps
t_{JITTER}	RMS Random Clock Jitter (Note 11)	f_{in} = 400 MHz			1	ps
V_{cross}	Absolute Crossing Magnitude Voltage		250		550	mV
ΔV_{cross}	Variation in Magnitude of V_{cross}				150	mV
t_r, t_f	Absolute Magnitude in Output Risetime and Falltime (From 175 mV to 525 mV)	Qx, $\overline{Qx}$	175	340	700	ps
Δt_r, Δt_f	Variation in Magnitude of Risetime and Falltime (Single−Ended) (See Figure 4)	Qx, $\overline{Qx}$			125	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

7. Measured by forcing V_{INPP} (MIN) from a 50% duty cycle clock source. Measurements taken with all outputs loaded 50 Ω to GND, see Figure 9. Typical gain is 20 dB.
8. Measured from the input pair crosspoint to each single output pair crosspoint across temp and voltage ranges.
9. Duty cycle skew is measured between differential outputs using the deviations of the sum of Tpw− and Tpw+.
10. Skew is measured between outputs under identical transition @ 400 MHz.
11. Additive RMS jitter with 50% duty cycle clock signal using phase noise integrated from 12 KHz to 33 MHz

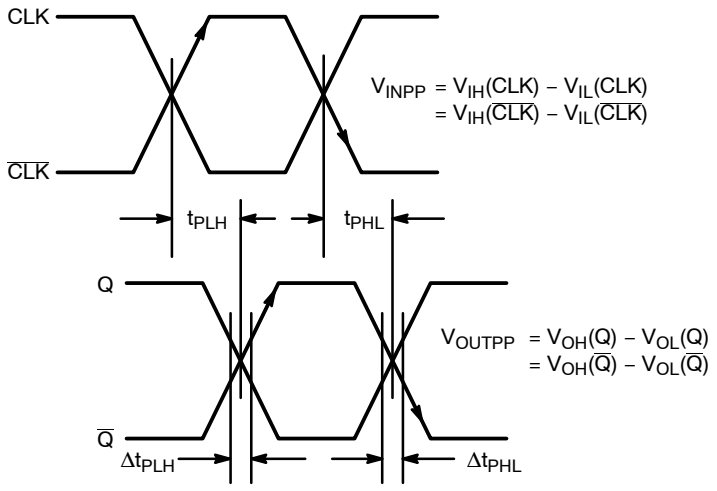


Figure 3. AC Reference Measurement

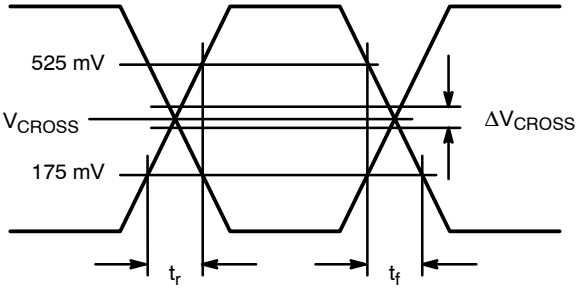


Figure 4. HCSL Output Parameter Characteristics

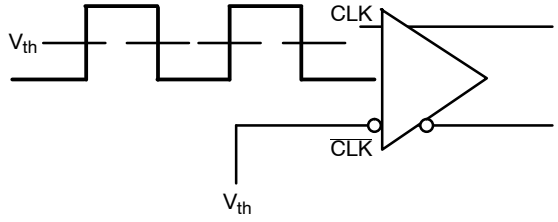


Figure 5. Differential Input Driven Single−Ended (V_{th} = V_{REFAC})

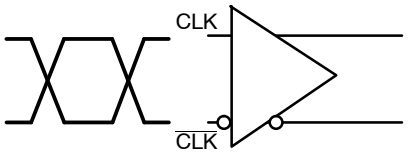


Figure 6. Differential Inputs Driven Differentially

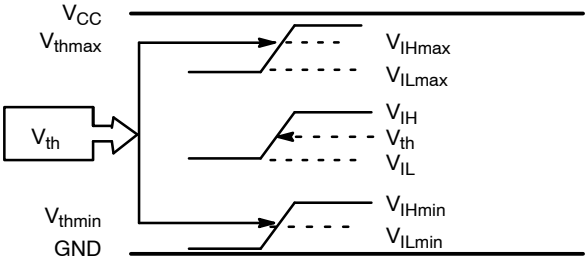


Figure 7. V_{th} Diagram

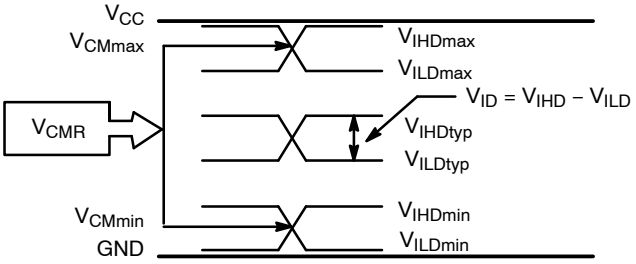
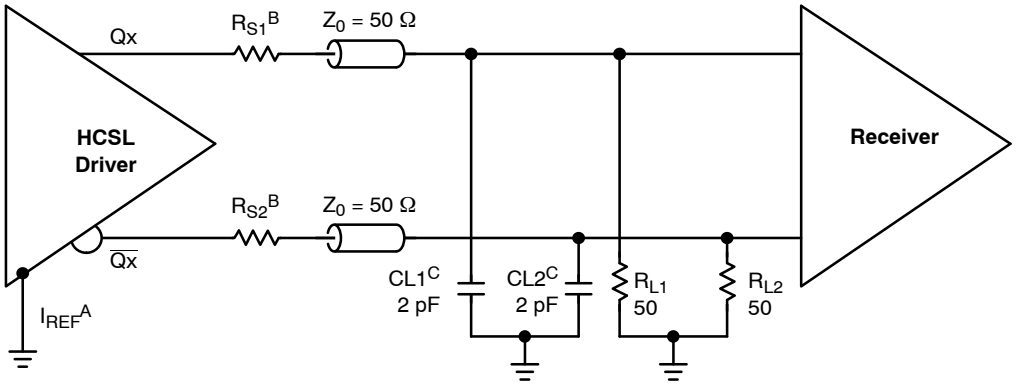
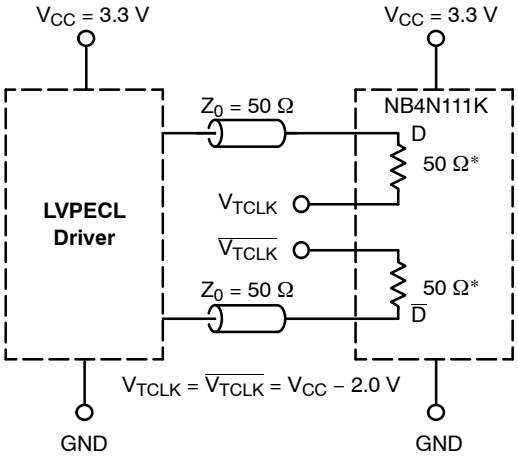


Figure 8. V_{CMR} Diagram



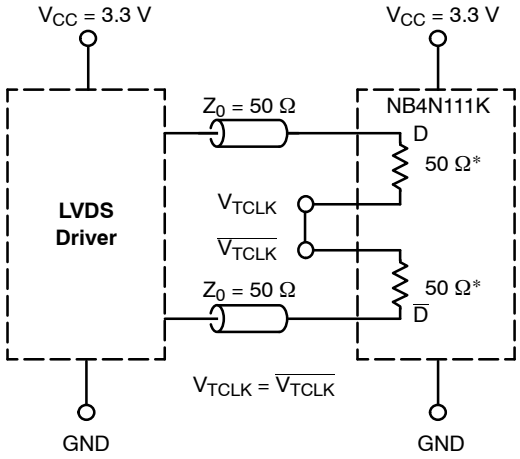
A. Connect $_{IREF}$ pin to GND.
B. RS1, RS2: 0 Ω for Test and Evaluation. Select to Minimizing Ringing.
C. CL1, CL2: Receiver Input Simulation Load Capacitance Only.

Figure 9. Typical Termination Configuration for Output Driver and Device Evaluation C_{Lx} for Test Only (Representing Receiver Input Loading); Not Added to Application



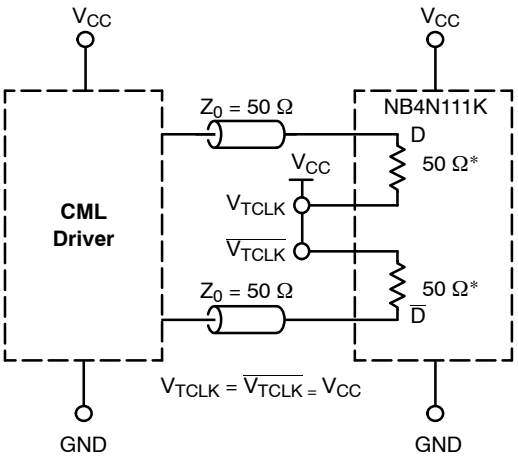
*RTIN, Internal Input Termination Resistor

Figure 10. LVPECL Interface



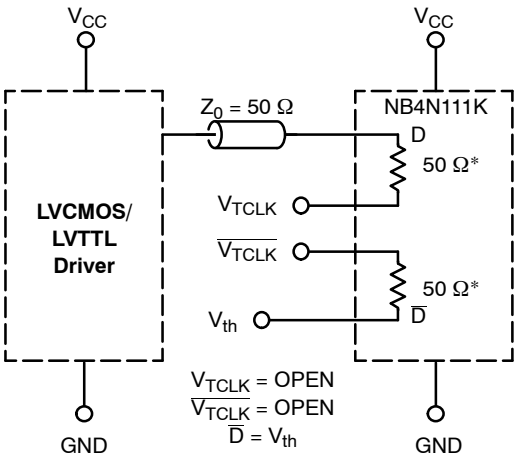
*RTIN, Internal Input Termination Resistor

Figure 11. LVDS Interface



*RTIN, Internal Input Termination Resistor

Figure 12. Standard 50 Ω Load CML Interface



*RTIN, Internal Input Termination Resistor

Figure 13. LVCMOS/LVTTL Interface

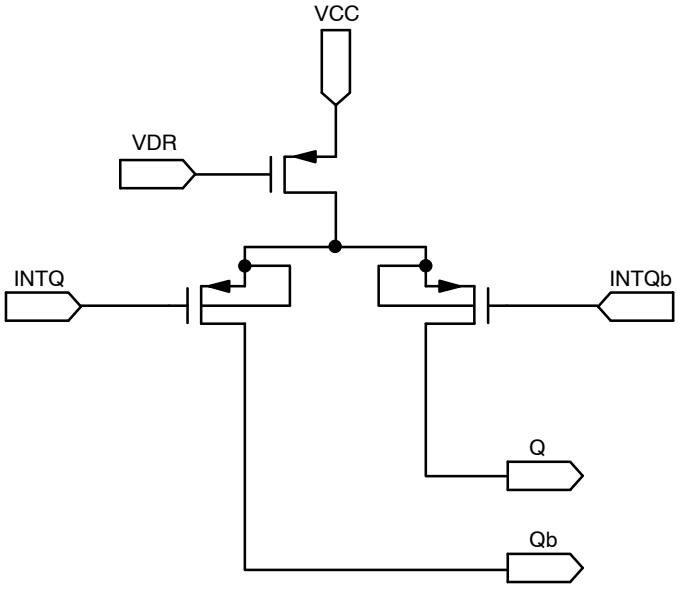


Figure 14. HCSL Output Structure

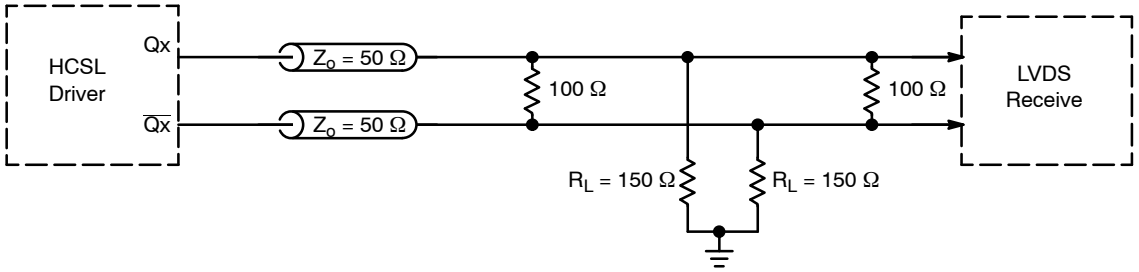


Figure 15. HCSL Interface Termination to LVDS

ORDERING INFORMATION

Device	Package	Shipping†
NB4N111KMNG	QFN32 (Pb−Free)	79 Units / Rail
NB4N111KMNR4G	QFN32 (Pb−Free)	1000 / Tape & Reel

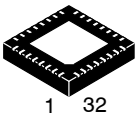
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

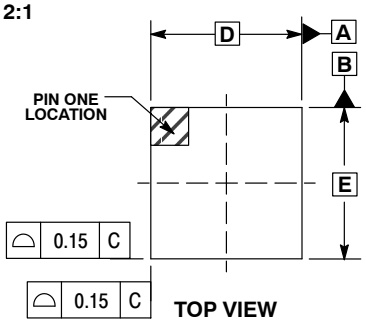
ON Semiconductor®

QFN32 5x5, 0.5P
CASE 488AM
ISSUE A

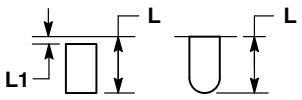
DATE 23 OCT 2013



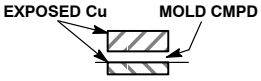
SCALE 2:1



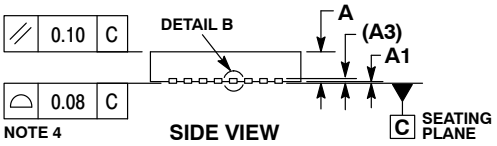
TOP VIEW



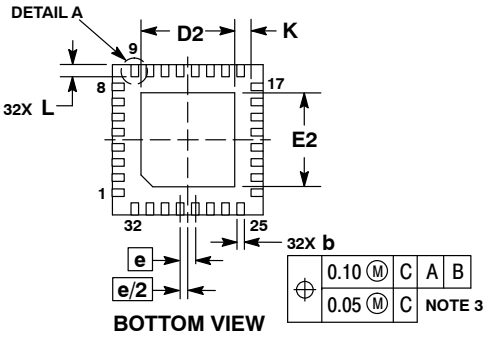
DETAIL A
ALTERNATE TERMINAL CONSTRUCTIONS



DETAIL B
ALTERNATE CONSTRUCTION



SIDE VIEW



BOTTOM VIEW

NOTES:
1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20 REF	
b	0.18	0.30
D	5.00 BSC	
D2	2.95	3.25
E	5.00 BSC	
E2	2.95	3.25
e	0.50 BSC	
K	0.20	---
L	0.30	0.50
L1	---	0.15

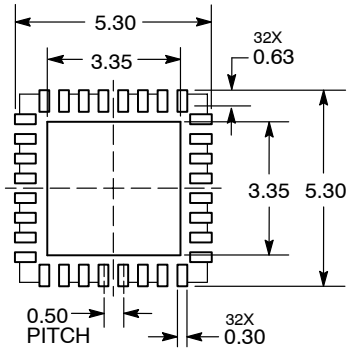
GENERIC MARKING DIAGRAM*

XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking.
Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSION: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	**98AON20032D**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**QFN32 5x5 0.5P**	**PAGE 1 OF 1**

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:
Technical Library: www.onsemi.com/design/resources/technical−documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support
For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales